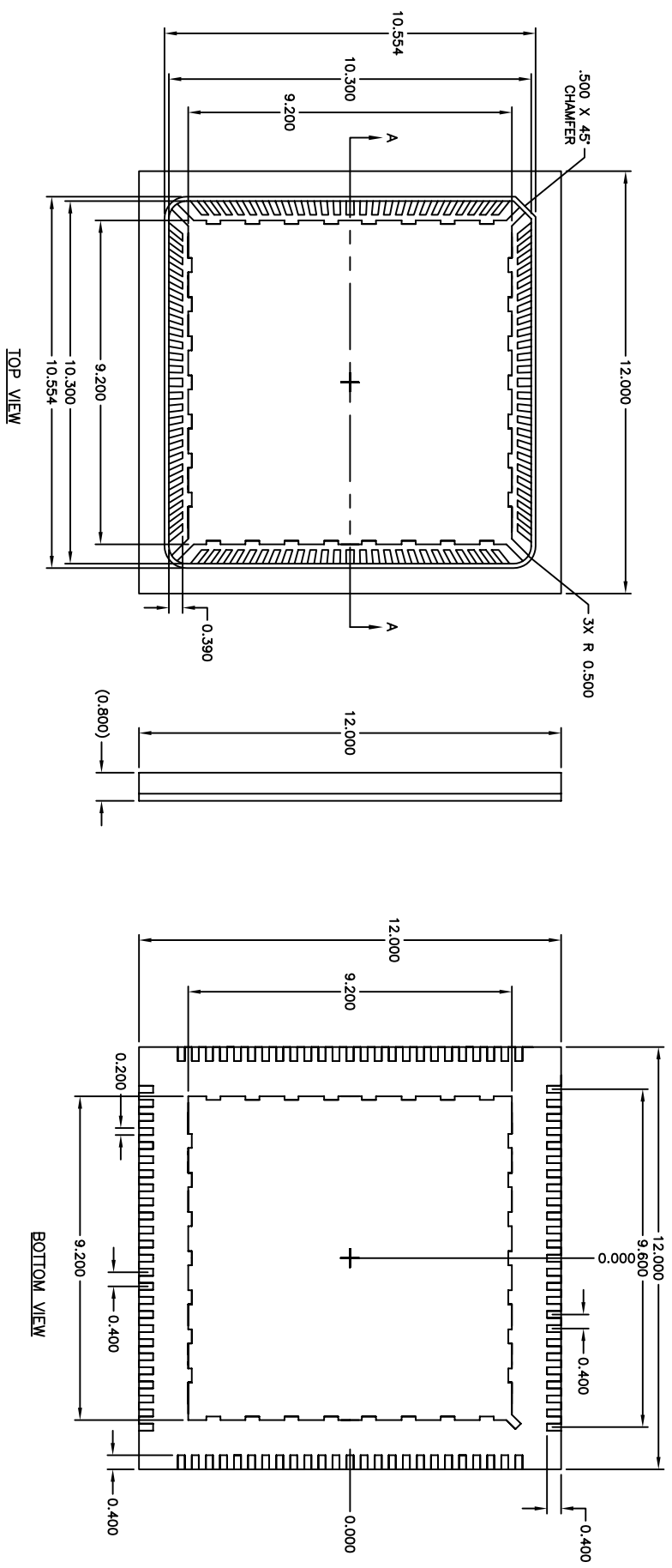
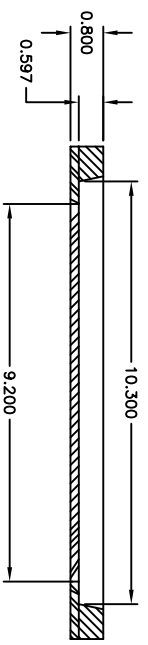


SEMPAC REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	
10956	01/16/07	PRODUCTION RELEASE	D.MORRIS



SECTION A-A



TOP VIEW

BOTTOM VIEW

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. LEAD FINISH: 0.2030 ±.0076
 5. FRAME THICKNESS: 0.2030 ±.0076
 6. DIE PAD: 9.200mm x 9.200mm.



THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XXX ±.015 X.XXX ±.0050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	C. CRUZ	DATE	11/30/06
APP BY	P. FLASKERUD	DATE	11/30/06
CUSTOMER	---		

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SIZE	PART NO.	REV
A	MLP12X12-100-0P-01	2
SCALE	NONE	
FILE	MLP12X12-100-0P-01-R2.DWG	
SHEET	1 OF 1	